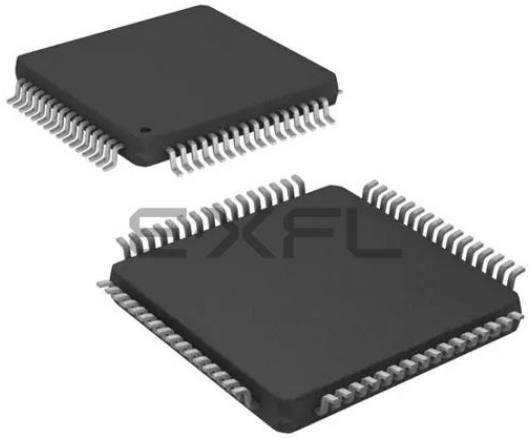

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, Motor Control PWM, POR, PWM, WDT
Number of I/O	53
Program Memory Size	512KB (170K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	48K x 8
Voltage - Supply (Vcc/Vdd)	-
Data Converters	A/D 30x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep512gm306t-i-pt

Allocating different Page registers for read and write access allows the architecture to support data movement between different pages in data memory. This is accomplished by setting the DSRPAG register value to the page from which you want to read and configuring the DSWPAG register to the page to which it needs to be written. Data can also be moved from different PSV to EDS pages by configuring the DSRPAG and DSWPAG registers to address PSV and EDS space, respectively. The data can be moved between pages by a single instruction.

When an EDS or PSV page overflow or underflow occurs, EA<15> is cleared as a result of the register indirect EA calculation. An overflow or underflow of the EA in the EDS or PSV pages can occur at the page boundaries when:

- The initial address, prior to modification, addresses an EDS or PSV page
- The EA calculation uses Pre- or Post-Modified Register Indirect Addressing. However, this does not include Register Offset Addressing

In general, when an overflow is detected, the DSxPAG register is incremented and the EA<15> bit is set to keep the base address within the EDS or PSV window. When an underflow is detected, the DSxPAG register is decremented and the EA<15> bit is set to keep the base address within the EDS or PSV window. This creates a linear EDS and PSV address space, but only when using Register Indirect Addressing modes.

Exceptions to the operation described above arise when entering and exiting the boundaries of Page 0, EDS and PSV spaces. Table 4-64 lists the effects of overflow and underflow scenarios at different boundaries.

In the following cases, when overflow or underflow occurs, the EA<15> bit is set and the DSxPAG is not modified; therefore, the EA will wrap to the beginning of the current page:

- Register Indirect with Register Offset Addressing
- Modulo Addressing
- Bit-Reversed Addressing

TABLE 4-64: OVERFLOW AND UNDERFLOW SCENARIOS AT PAGE 0, EDS AND PSV SPACE BOUNDARIES(2,3,4)

O/U, R/W	Operation	Before			After		
		DSxPAG	DS EA<15>	Page Description	DSxPAG	DS EA<15>	Page Description
O, Read	[++Wn] or [Wn++]	DSRPAG = 0x1FF	1	EDS: Last Page	DSRPAG = 0x1FF	0	See **Note 1**
O, Read		DSRPAG = 0x2FF	1	PSV: Last lsw Page	DSRPAG = 0x300	1	PSV: First MSB Page
O, Read		DSRPAG = 0x3FF	1	PSV: Last MSB Page	DSRPAG = 0x3FF	0	See **Note 1**
O, Write		DSWPAG = 0x1FF	1	EDS: Last Page	DSWPAG = 0x1FF	0	See **Note 1**
U, Read	[--Wn] or [Wn--]	DSRPAG = 0x001	1	PSV Page	DSRPAG = 0x001	0	See **Note 1**
U, Read		DSRPAG = 0x200	1	PSV: First lsw Page	DSRPAG = 0x200	0	See **Note 1**
U, Read		DSRPAG = 0x300	1	PSV: First MSB Page	DSRPAG = 0x2FF	1	PSV: Last lsw Page

Legend: O = Overflow, U = Underflow, R = Read, W = Write

Note 1: The Register Indirect Addressing now addresses a location in the Base Data Space (0x0000-0x8000).

2: An EDS access with DSxPAG = 0x000 will generate an address error trap.

3: Only reads from PS are supported using DSRPAG. An attempt to write to PS using DSWPAG will generate an address error trap.

4: Pseudo Linear Addressing is not supported for large offsets.

REGISTER 9-1: OSCCON: OSCILLATOR CONTROL REGISTER(1,3)

U-0	R-0	R-0	R-0	U-0	R/W-y	R/W-y	R/W-y
—	COSC2	COSC1	COSC0	—	NOSC2(2)	NOSC1(2)	NOSC0(2)
bit 15							bit 8

R/W-0	R/W-0	R-0	U-0	R/W-0	U-0	R/W-0	R/W-0
CLKLOCK	IOLOCK	LOCK	—	CF(5)	—	LPOSCEN	OSWEN
bit 7							bit 0

Legend:	y = Value set from Configuration bits on POR		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **COSC<2:0>:** Current Oscillator Selection bits (read-only)
111 = Fast RC Oscillator (FRC) with Divide-by-N
110 = Fast RC Oscillator (FRC) with Divide-by-16
101 = Low-Power RC Oscillator (LPRC)
100 = Secondary Oscillator (SOSC)(4)
011 = Primary Oscillator (MS, HS, EC) with PLL
010 = Primary Oscillator (MS, HS, EC)
001 = Fast RC Oscillator (FRC) Divided by N and PLL
000 = Fast RC Oscillator (FRC)

bit 11 **Unimplemented:** Read as '0'

bit 10-8 **NOSC<2:0>:** New Oscillator Selection bits(2)
111 = Fast RC Oscillator (FRC) with Divide-by-N
110 = Fast RC Oscillator (FRC) with Divide-by-16
101 = Low-Power RC Oscillator (LPRC)
100 = Secondary Oscillator (SOSC)(4)
011 = Primary Oscillator (MS, HS, EC) with PLL
010 = Primary Oscillator (MS, HS, EC)
001 = Fast RC Oscillator (FRC) Divided by N and PLL
000 = Fast RC Oscillator (FRC)

bit 7 **CLKLOCK:** Clock Lock Enable bit
1 = If FCKSM0 = 1, then clock and PLL configurations are locked; if FCKSM0 = 0, then clock and PLL configurations may be modified
0 = Clock and PLL selections are not locked, configurations may be modified

bit 6 **IOLOCK:** I/O Lock Enable bit
1 = I/O lock is active
0 = I/O lock is not active

Note 1: Writes to this register require an unlock sequence. Refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"Oscillator"** (DS70580), available from the Microchip web site for details.

2: Direct clock switches between any primary oscillator mode with PLL and FRCPLL mode are not permitted. This applies to clock switches in either direction. In these instances, the application must switch to FRC mode as a transitional clock source between the two PLL modes.

3: This register resets only on a Power-on Reset (POR).

4: Secondary Oscillator (SOSC) selection is valid on 64-pin and 100-pin devices, and defaults to FRC/N on 44-pin devices.

5: Only '0' should be written to the CF bit in order to clear it. If a '1' is written to CF, it will have the same effect as a detected clock failure, including an oscillator fail trap.

REGISTER 11-23: RPINR29: PERIPHERAL PIN SELECT INPUT REGISTER 29

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	SCK3R<6:0>						
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	SDI3R<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-8 **SCK3R<6:0>:** Assign SPI3 Clock Input (SCK3) to the Corresponding RPn/RPIn Pin bits (see Table 11-2 for input pin selection numbers)

1111111 = Input tied to RP124
•
•
•
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

bit 7 **Unimplemented:** Read as ‘0’

bit 6-0 **SDI3R<6:0>:** Assign SPI3 Data Input (SDI3) to the Corresponding RPn/RPIn Pin bits (see Table 11-2 for input pin selection numbers)

1111111 = Input tied to RP124
•
•
•
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

13.0 TIMER2/3, TIMER4/5, TIMER6/7 AND TIMER8/9

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGM3XX/6XX/7XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"Timers"** (DS70362), which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Timer2/3, Timer4/5, Timer6/7 and Timer8/9 modules are 32-bit timers, which can also be configured as eight independent 16-bit timers with selectable operating modes.

As a 32-bit timer, Timer2/3, Timer4/5, Timer6/7 and Timer8/9 operate in three modes:

- Two Independent 16-Bit Timers (e.g., Timer2 and Timer3) with All 16-Bit Operating modes (except Asynchronous Counter mode)
- Single 32-Bit Timer
- Single 32-Bit Synchronous Counter

They also support these features:

- Timer Gate Operation
- Selectable Prescaler Settings
- Timer Operation during Idle and Sleep modes
- Interrupt on a 32-Bit Period Register Match
- Time Base for Input Capture and Output Compare modules
- ADC1 Event Trigger (Timer2/3 only)

Individually, all eight of the 16-bit timers can function as synchronous timers or counters. They also offer the features listed previously, except for the event trigger; this is implemented only with Timer2/3. The operating modes and enabled features are determined by setting the appropriate bit(s) in the T2CON, T3CON, T4CON, T5CON, T6CON, T7CON, T8CON and T9CON registers. T2CON, T4CON, T6CON and T8CON are shown in generic form in Register 13-1. T3CON, T5CON, T7CON and T9CON are shown in Register 13-2.

For 32-bit timer/counter operation, Timer2, Timer4, Timer6 and Timer8 are the least significant word (lsw); Timer3, Timer5, Timer7 and Timer9 are the most significant word (msw) of the 32-bit timers.

Note: For 32-bit operation, T3CON, T5CON, T7CON and T9CON register control bits are ignored. Only T2CON, T4CON, T6CON and T8CON register control bits are used for setup and control. Timer2, Timer4, Timer6 and Timer8 clock and gate inputs are utilized for the 32-bit timer modules, but an interrupt is generated with the Timer3, Timer5, Timer7 and Timer9 interrupt flags.

A block diagram for an example of a 32-bit timer pair (Timer2/3 and Timer4/5) is shown in Figure 13-3.

Note: Only Timer2, 3, 4 and 5 can trigger a DMA data transfer.

REGISTER 16-19: IOCONx: PWMx I/O CONTROL REGISTER(2) (CONTINUED)

bit 1 **SWAP:** SWAP PWMxH and PWMxL Pins bit
1 = PWMxH output signal is connected to the PWMxL pins; PWMxL output signal is connected to the PWMxH pins
0 = PWMxH and PWMxL pins are mapped to their respective pins

bit 0 **OSYNC:** Output Override Synchronization bit
1 = Output overrides via the OVRDAT<1:0> bits are synchronized to the PWM time base
0 = Output overrides via the OVDDAT<1:0> bits occur on the next CPU clock boundary

Note 1: These bits should not be changed after the PWMx module is enabled (PTEN = 1).
2: If the PWMLOCK Configuration bit (FOSCSEL<6>) is a '1', the IOCONx register can only be written after the unlock sequence has been executed.

REGISTER 16-20: TRIGx: PWMx PRIMARY TRIGGER COMPARE VALUE REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
TRGCMP<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
TRGCMP<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **TRGCMP<15:0>:** Trigger Control Value bits
When the primary PWMx functions in the local time base, this register contains the compare values that can trigger the ADCx module.

18.0 SERIAL PERIPHERAL INTERFACE (SPI)

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGM3XX/6XX/7XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"Serial Peripheral Interface (SPI)"** (DS70005185), which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The SPI module is a synchronous serial interface, useful for communicating with other peripheral or microcontroller devices. These peripheral devices can be serial EEPROMs, shift registers, display drivers, A/D Converters, etc. The SPI module is compatible with the Motorola® SPI and SIOP interfaces.

The dsPIC33EPXXXGM3XX/6XX/7XX device family offers three SPI modules on a single device. These modules, which are designated as SPI1, SPI2 and SPI3, are functionally identical. Each SPI module includes an eight-word FIFO buffer and allows DMA bus connections. When using the SPI module with DMA, FIFO operation can be disabled.

Note: In this section, the SPI modules are referred to together as SPIx, or separately as SPI1, SPI2 and SPI3. Special Function Registers follow a similar notation. For example, SPIxCON refers to the control register for the SPI1, SPI2 and SPI3 modules.

The SPI1 module uses dedicated pins which allow for a higher speed when using SPI1. The SPI2 and SPI3 modules take advantage of the Peripheral Pin Select (PPS) feature to allow for greater flexibility in pin configuration of these modules, but results in a lower maximum speed. See **Section 33.0 "Electrical Characteristics"** for more information.

The SPIx serial interface consists of four pins, as follows:

- SDIx: Serial Data Input
- SDOx: Serial Data Output
- SCKx: Shift Clock Input or Output
- $\overline{SS}$x/FSYNCx: Active-Low Slave Select or Frame Synchronization I/O Pulse

The SPIx module can be configured to operate with two, three or four pins. In 3-pin mode, $\overline{SS}$x is not used. In 2-pin mode, neither SDOx nor $\overline{SS}$x is used.

Figure 18-1 illustrates the block diagram of the SPIx module in Standard and Enhanced modes.

BUFFER 21-7: CANx MESSAGE BUFFER WORD 6

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 7<15:8>							
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 6<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Byte 7<15:8>:** CANx Message Byte 7

bit 7-0 **Byte 6<7:0>:** CANx Message Byte 6

BUFFER 21-8: CANx MESSAGE BUFFER WORD 7

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	FILHIT<4:0>(1)				
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12-8 **FILHIT<4:0>:** Filter Hit Code bits(1)
Encodes number of filter that resulted in writing this buffer.

bit 7-0 **Unimplemented:** Read as '0'

Note 1: Only written by module for receive buffers, unused for transmit buffers.

REGISTER 23-3: ADxCON3: ADCx CONTROL REGISTER 3

R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADRC	—	—	SAMC4(1)	SAMC3(1)	SAMC2(1)	SAMC1(1)	SAMC0(1)
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADCS7(2)	ADCS6(2)	ADCS5(2)	ADCS4(2)	ADCS3(2)	ADCS2(2)	ADCS1(2)	ADCS0(2)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ADRC:** ADCx Conversion Clock Source bit
1 = ADCx internal RC clock
0 = Clock derived from system clock

bit 14-13 **Unimplemented:** Read as '0'

bit 12-8 **SAMC<4:0>:** Auto-Sample Time bits(1)
11111 = 31 TAD
•
•
•
00001 = 1 TAD
00000 = 0 TAD

bit 7-0 **ADCS<7:0>:** ADCx Conversion Clock Select bits(2)
11111111 = TP • (ADCS<7:0> + 1) = TP • 256 = TAD
•
•
•
00000010 = TP • (ADCS<7:0> + 1) = TP • 3 = TAD
00000001 = TP • (ADCS<7:0> + 1) = TP • 2 = TAD
00000000 = TP • (ADCS<7:0> + 1) = TP • 1 = TAD

Note 1: This bit is only used if SSRC<2:0> (AD1CON1<7:5>) = 111 and SSRCG (AD1CON1<4>) = 0.
2: This bit is not used if ADRC (AD1CON3<15>) = 1.

REGISTER 26-3: CM4CON: OP AMP/COMPARATOR 4 CONTROL REGISTER (CONTINUED)

bit 7-6 **EVPOL<1:0>:** Trigger/Event/Interrupt Polarity Select bits(2)

11 = Trigger/event/interrupt generated on any change of the comparator output (while CEVT = 0)

10 = Trigger/event/interrupt generated only on high-to-low transition of the polarity selected comparator output (while CEVT = 0)

If CPOL = 1 (inverted polarity):
Low-to-high transition of the comparator output.

If CPOL = 0 (non-inverted polarity):
High-to-low transition of the comparator output.

01 = Trigger/event/interrupt generated only on low-to-high transition of the polarity selected comparator output (while CEVT = 0)

If CPOL = 1 (inverted polarity):
High-to-low transition of the comparator output.

If CPOL = 0 (non-inverted polarity):
Low-to-high transition of the comparator output.

00 = Trigger/event/interrupt generation is disabled

bit 5 **Unimplemented:** Read as '0'

bit 4 **CREF:** Comparator Reference Select bit (VIN+ input)(1)

1 = VIN+ input connects to internal CVREFIN voltage

0 = VIN+ input connects to C4IN1+ pin

bit 3-2 **Unimplemented:** Read as '0'

bit 1-0 **CCH<1:0>:** Comparator Channel Select bits(1)

11 = VIN- input of comparator connects to OA3/AN6

10 = VIN- input of comparator connects to OA2/AN0

01 = VIN- input of comparator connects to OA1/AN3

00 = VIN- input of comparator connects to C4IN1-

Note 1: Inputs that are selected and not available will be tied to VSS. See the **"Pin Diagrams"** section for available inputs for each package.

2: After configuring the comparator, either for a high-to-low or low-to-high COUT transition (EVPOL<1:0> (CMxCON<7:6>) = 10 or 01), the Comparator Event bit, CEVT (CMxCON<9>), and the Comparator Combined Interrupt Flag, CMPIF (IFS1<2>), **must be cleared** before enabling the Comparator Interrupt Enable bit, CMPIE (IEC1<2>).

30.2 User ID Words

dsPIC33EPXXXGM3XX/6XX/7XX devices contain four User ID Words, located at addresses, 0x800FF8 through 0x800FFE. The User ID Words can be used for storing product information, such as serial numbers, system manufacturing dates, manufacturing lot numbers and other application-specific information.

The User ID Words register map is shown in Table 30-3.

TABLE 30-3: USER ID WORDS REGISTER MAP

File Name	Address	Bits<23:16>	Bits<15:0>
FUID0	0x800FF8	—	UID0
FUID1	0x800FFA	—	UID1
FUID2	0x800FFC	—	UID2
FUID3	0x800FFE	—	UID3

Legend: — = unimplemented, read as '1'.

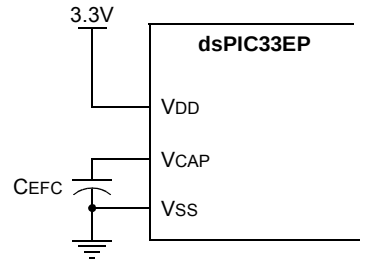
30.3 On-Chip Voltage Regulator

All of the dsPIC33EPXXXGM3XX/6XX/7XX devices power their core digital logic at a nominal 1.8V. This can create a conflict for designs that are required to operate at a higher typical voltage, such as 3.3V. To simplify system design, all devices in the dsPIC33EPXXXGM3XX/6XX/7XX family incorporate an on-chip regulator that allows the device to run its core logic from VDD.

The regulator provides power to the core from the other VDD pins. A low-ESR (less than 1 Ohm) capacitor (such as tantalum or ceramic) must be connected to the VCAP pin (Figure 30-1). This helps to maintain the stability of the regulator. The recommended value for the filter capacitor is provided in Table 33-5, located in **Section 33.0 "Electrical Characteristics"**.

Note:	It is important for the low-ESR capacitor to be placed as close as possible to the VCAP pin.

FIGURE 30-1: CONNECTIONS FOR THE ON-CHIP VOLTAGE REGULATOR(1,2,3)



Note 1: These are typical operating voltages. Refer to Table 33-5 located in **Section 33.1 "DC Characteristics"** for the full operating ranges of VDD and VCAP.

2: It is important for the low-ESR capacitor to be placed as close as possible to the VCAP pin.

3: Typical VCAP pin voltage = 1.8V when VDD ≥ VDDMIN.

30.4 Brown-out Reset (BOR)

The Brown-out Reset (BOR) module is based on an internal voltage reference circuit that monitors the regulated supply voltage, VCAP. The main purpose of the BOR module is to generate a device Reset when a brown-out condition occurs. Brown-out conditions are generally caused by glitches on the AC mains (for example, missing portions of the AC cycle waveform due to bad power transmission lines or voltage sags due to excessive current draw when a large inductive load is turned on).

A BOR generates a Reset pulse, which resets the device. The BOR selects the clock source, based on the device Configuration bit values (FNOSC<2:0> and POSCMD<1:0>).

If an oscillator mode is selected, the BOR activates the Oscillator Start-up Timer (OST). The system clock is held until OST expires. If the PLL is used, the clock is held until the LOCK bit (OSCCON<5>) is '1'.

Concurrently, the Power-up Timer (PWRT) Time-out (TPWRT) is applied before the internal Reset is released. If TPWRT = 0 and a crystal oscillator is being used, then a nominal delay of TFSCM is applied. The total delay in this case is TFSCM. Refer to Parameter SY35 in Table 33-21 of **Section 33.0 "Electrical Characteristics"** for specific TFSCM values.

The BOR Status bit (RCON<1>) is set to indicate that a BOR has occurred. The BOR circuit continues to operate while in Sleep or Idle mode and resets the device should VDD fall below the BOR threshold voltage.

30.6 JTAG Interface

dsPIC33EPXXXGM3XX/6XX/7XX devices implement a JTAG interface, which supports boundary scan device testing. Detailed information on this interface is provided in future revisions of the document.

Note: Refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"Programming and Diagnostics"** (DS70608) for further information on usage, configuration and operation of the JTAG interface.

30.7 In-Circuit Serial Programming

The dsPIC33EPXXXGM3XX/6XX/7XX devices can be serially programmed while in the end application circuit. This is done with two lines for clock and data, and three other lines for power, ground and the programming sequence. Serial programming allows customers to manufacture boards with unprogrammed devices and then program the device just before shipping the product. Serial programming also allows the most recent firmware or a custom firmware to be programmed. Refer to the *"dsPIC33E/PIC24E Flash Programming Specification for Devices with Volatile Configuration Bits"* (DS70663) for details about In-Circuit Serial Programming (ICSP).

Any of the three pairs of programming clock/data pins can be used:

- PGEC1 and PGED1
- PGEC2 and PGED2
- PGEC3 and PGED3

30.8 In-Circuit Debugger

When MPLAB® ICD 3 or the REAL ICE™ in-circuit emulator is selected as a debugger, the in-circuit debugging functionality is enabled. This function allows simple debugging functions when used with MPLAB X IDE. Debugging functionality is controlled through the PGECx (Emulation/Debug Clock) and PGEDx (Emulation/Debug Data) pin functions.

Any of the three pairs of debugging clock/data pins can be used:

- PGEC1 and PGED1
- PGEC2 and PGED2
- PGEC3 and PGED3

To use the in-circuit debugger function of the device, the design must implement ICSP connections to $\overline{MCLR}$, V_{DD}, V_{SS} and the PGECx/PGEDx pin pair. In addition, when the feature is enabled, some of the resources are not available for general use. These resources include the first 80 bytes of data RAM and two I/O pins (PGECx and PGEDx).

30.9 Code Protection and CodeGuard™ Security

The dsPIC33EPXXXGM3XX/6XX/7XX devices offer basic implementation of CodeGuard Security that supports only General Segment (GS) security. This feature helps protect individual Intellectual Property.

Note: Refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"CodeGuard™ Security"** (DS70634) for further information on usage, configuration and operation of CodeGuard Security.

FIGURE 33-2: EXTERNAL CLOCK TIMING

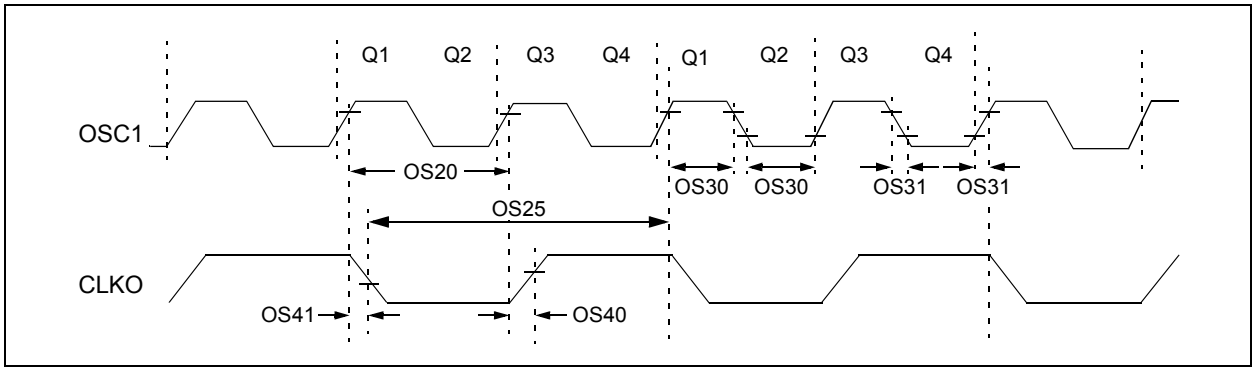


TABLE 33-16: EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symb**	**Characteristic**	**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
OS10	FIN	External CLKI Frequency (External clocks allowed only in EC and ECPLL modes)	DC	—	60	MHz	EC
		Oscillator Crystal Frequency	3.5 10 32.4	— — 32.768	10 25 33.1	MHz MHz kHz	XT HS SOSC
OS20	TOSC	TOSC = 1/FOSC	8.33	—	DC	ns	TA = +125ºC
		TOSC = 1/FOSC	7.14	—	DC	ns	TA = +85ºC
OS25	TCY	Instruction Cycle Time(2)	16.67	—	DC	ns	TA = +125ºC
			14.28	—	DC	ns	TA = +85ºC
OS30	TosL, TosH	External Clock in (OSC1) High or Low Time	0.375 x TOSC	—	0.625 x TOSC	ns	EC
OS31	TosR, TosF	External Clock in (OSC1) Rise or Fall Time	—	—	20	ns	EC
OS40	TckR	CLKO Rise Time(3)	—	5.2	—	ns	
OS41	TckF	CLKO Fall Time(3)	—	5.2	—	ns	
OS42	GM	External Oscillator Transconductance(4)	—	12	—	mA/V	HS, VDD = 3.3V, TA = +25ºC
			—	6	—	mA/V	XT, VDD = 3.3V, TA = +25ºC

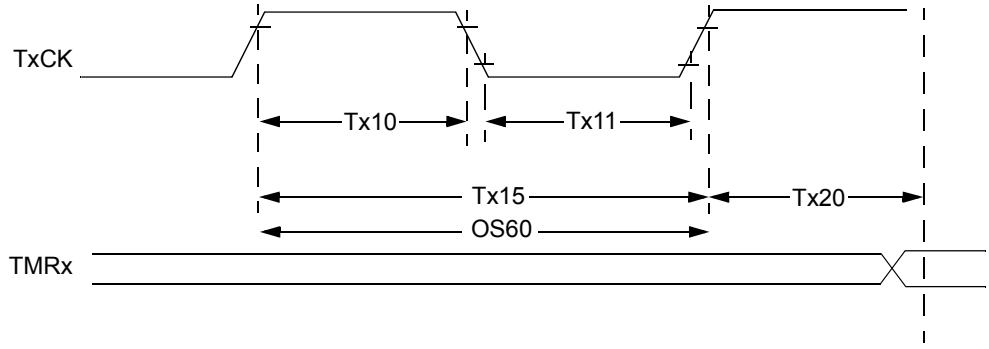
Note 1: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

2: Instruction cycle period (TCY) equals two times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at “Minimum” values with an external clock applied to the OSC1 pin. When an external clock input is used, the “Maximum” cycle time limit is “DC” (no clock) for all devices.

3: Measurements are taken in EC mode. The CLKO signal is measured on the OSC2 pin.

4: This parameter is characterized, but not tested in manufacturing.

FIGURE 33-6: TIMER1-TIMER5 EXTERNAL CLOCK TIMING CHARACTERISTICS



Note: Refer to Figure 33-1 for load conditions.

TABLE 33-22: TIMER1 EXTERNAL CLOCK TIMING REQUIREMENTS(1)

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(2)**		**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
TA10	TTXH	T1CK High Time	Synchronous mode	Greater of: 20 or (TCY + 20)/N	—	—	ns	Must also meet Parameter TA15, N = Prescaler value (1, 8, 64, 256)
			Asynchronous	35	—	—	ns	
TA11	TTXL	T1CK Low Time	Synchronous mode	Greater of: 20 or (TCY + 20)/N	—	—	ns	Must also meet Parameter TA15, N = Prescaler value (1, 8, 64, 256)
			Asynchronous	10	—	—	ns	
TA15	TTXP	T1CK Input Period	Synchronous mode	Greater of: 40 or (2 TCY + 40)/N	—	—	ns	N = Prescaler value (1, 8, 64, 256)
OS60	Ft1	T1CK Oscillator Input Frequency Range (oscillator enabled by setting TCS (T1CON<1>) bit)		DC	—	50	kHz	
TA20	TCKEXTMRL	Delay from External T1CK Clock Edge to Timer Increment		0.75 TCY + 40	—	1.75 TCY + 40	ns	

Note 1: Timer1 is a Type A.

2: These parameters are characterized, but are not tested in manufacturing.

TABLE 33-23: TIMER2 AND TIMER4 (TYPE B TIMER) EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**		**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
TB10	TTXH	TxCK High Time	Synchronous mode	Greater of: 20 or (TCY + 20)/N	—	—	ns	Must also meet Parameter TB15, N = Prescale value (1, 8, 64, 256)
TB11	TTXL	TxCK Low Time	Synchronous mode	Greater of: 20 or (TCY + 20)/N	—	—	ns	Must also meet Parameter TB15, N = Prescale value (1, 8, 64, 256)
TB15	TTXP	TxCK Input Period	Synchronous mode	Greater of: 40 or (2 TCY + 40)/N	—	—	ns	N = Prescale value (1, 8, 64, 256)
TB20	TCKEXTMRL	Delay from External TxCK Clock Edge to Timer Increment		0.75 TCY + 40	—	1.75 TCY + 40	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

TABLE 33-24: TIMER3 AND TIMER5 (TYPE C TIMER) EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**		**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
TC10	TTXH	TxCK High Time	Synchronous	TCY + 20	—	—	ns	Must also meet Parameter TC15
TC11	TTXL	TxCK Low Time	Synchronous	TCY + 20	—	—	ns	Must also meet Parameter TC15
TC15	TTXP	TxCK Input Period	Synchronous, with Prescaler	2 TCY + 40	—	—	ns	N = Prescale value (1, 8, 64, 256)
TC20	TCKEXTMRL	Delay from External TxCK Clock Edge to Timer Increment		0.75 TCY + 40	—	1.75 TCY + 40	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

FIGURE 33-19: SPI2 AND SPI3 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING CHARACTERISTICS

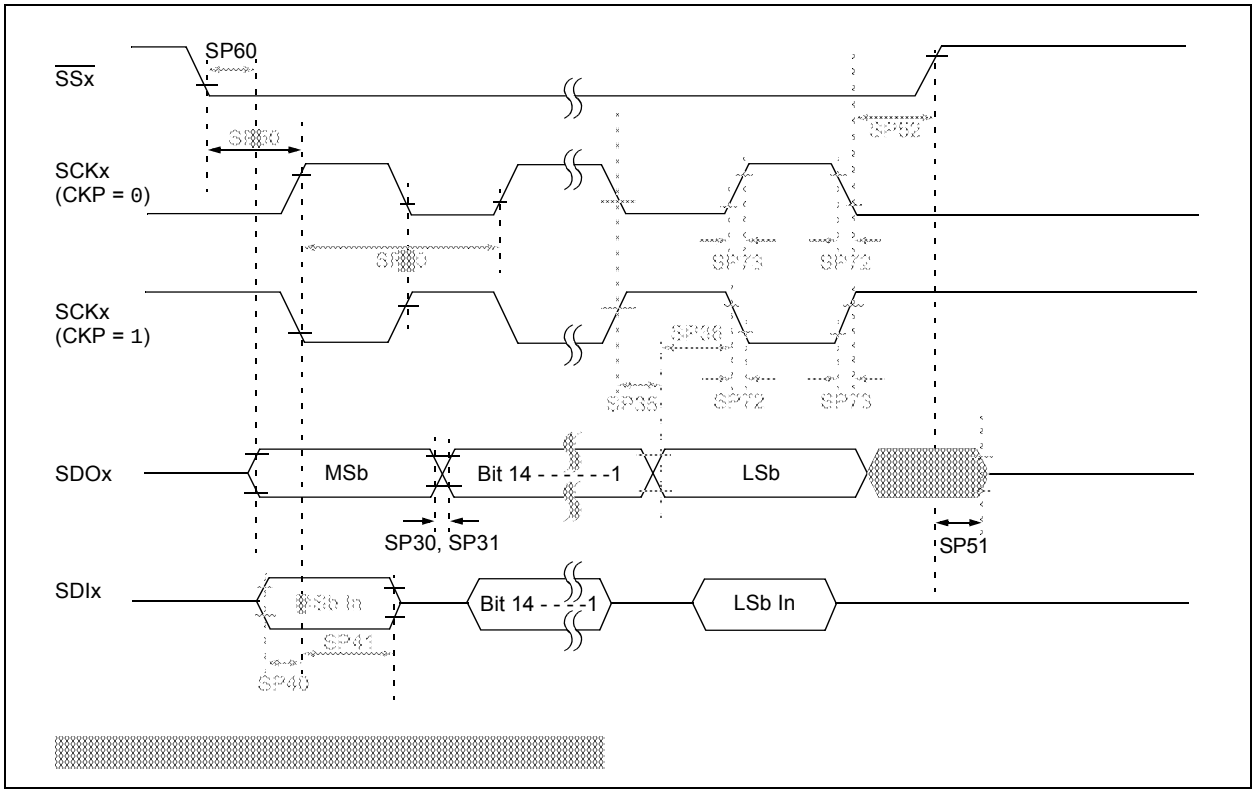


TABLE 33-39: SPI2 AND SPI3 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCKx Input Frequency	—	—	11	MHz	**(Note 3)**
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓ to SCKx ↑ or SCKx ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH TscL2ssH	$\overline{SSx}$ ↑ after SCKx Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 91 ns. Therefore, the SCKx clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

TABLE 33-46: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK1 Input Frequency	—	—	25	MHz	**(Note 3)**
SP72	TscF	SCK1 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK1 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	20	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	20	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	15	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS1}$ ↓ to SCK1 ↑ or SCK1 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS1}$ ↑ to SDO1 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH, TscL2ssH	$\overline{SS1}$ ↑ after SCK1 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 66.7 ns. Therefore, the SCK1 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

TABLE 33-58: ADCx MODULE SPECIFICATIONS (10-BIT MODE)

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)(1) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
ADC Accuracy (10-Bit Mode)							
AD20b	Nr	Resolution	10 Data Bits			bits	
AD21b	INL	Integral Nonlinearity	-0.625	—	0.625	LSb	-40°C ≤ TA ≤ +85°C **(Note 2)**
			-1.5	—	1.5	LSb	+85°C < TA ≤ +125°C **(Note 2)**
AD22b	DNL	Differential Nonlinearity	-0.25	—	0.25	LSb	-40°C ≤ TA ≤ +85°C **(Note 2)**
			-0.25	—	0.25	LSb	+85°C < TA ≤ +125°C **(Note 2)**
AD23b	GERR	Gain Error	-2.5	—	2.5	LSb	-40°C ≤ TA ≤ +85°C **(Note 2)**
			-2.5	—	2.5	LSb	+85°C < TA ≤ +125°C **(Note 2)**
AD24b	EOFF	Offset Error	-1.25	—	1.25	LSb	-40°C ≤ TA ≤ +85°C **(Note 2)**
			-1.25	—	1.25	LSb	+85°C < TA ≤ +125°C **(Note 2)**
AD25b	—	Monotonicity	—	—	—	—	Guaranteed
Dynamic Performance (10-Bit Mode)							
AD30b	THD	Total Harmonic Distortion(3)	—	64	—	dB	
AD31b	SINAD	Signal to Noise and Distortion(3)	—	57	—	dB	
AD32b	SFDR	Spurious Free Dynamic Range(3)	—	72	—	dB	
AD33b	FNYQ	Input Signal Bandwidth(3)	—	550	—	kHz	
AD34b	ENOB	Effective Number of Bits(3)	—	9.4	—	bits	

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules: ADC, op amp/comparator and comparator voltage reference, may have degraded performance. Refer to Parameter BO10 in Table 33-12 for the minimum and maximum BOR values.

2: For all accuracy specifications, VINL = AVSS = VREFL = 0V and AVDD = VREFH = 3.6V.

3: Parameters are characterized but not tested in manufacturing.

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